

## PATENT ASSIGNMENT COVER SHEET

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<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOUHEI ODA	09/19/2014
YOSHITAKA NODA	09/24/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	DENSO CORPORATION
<b>Street Address:</b>	1-1, SHOWA-CHO
<b>City:</b>	KARIYA-CITY, AICHI-PREF.
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	448-8661
<b>PROPERTY NUMBERS Total: 1</b>	
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<b>Application Number:</b>	14391038
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)707-9112
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	703 707 9110
<b>Email:</b>	mailbox@poszlaw.com
<b>Correspondent Name:</b>	POSZ LAW GROUP, PLC
<b>Address Line 1:</b>	12040 SOUTH LAKES DRIVE
<b>Address Line 2:</b>	SUITE 101
<b>Address Line 4:</b>	RESTON, VIRGINIA 20191
<b>ATTORNEY DOCKET NUMBER:</b>	01_2499_TN
<b>NAME OF SUBMITTER:</b>	DAVID G. POSZ
<b>SIGNATURE:</b>	/David G. Posz/
<b>DATE SIGNED:</b>	10/07/2014
<b>Total Attachments: 2</b>	
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譲受者名:  
Assignee(s):

住所:  
Address(es):

DENSO CORPORATION

1-1, Showa-cho, Kariya-city, Aichi-pref., 448-8661 Japan

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発明の名称:  
Title of  
Invention:

MANUFACTURING METHOD OF SEMICONDUCTOR SUBSTRATE

上記発明についての米国登録特許証の出願は、  
described in an application for Letters Patent of the United States executed

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- ☐ 米国出願番号 \_\_\_\_\_ として \_\_\_\_\_ に提出されたものです。  
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発明者はここに付随する添付書面上にリストされます。  
inventor(s) listed on the attached sheet which is incorporated herein by reference.

注記: 上記日本語抄訳は、本書面の理解の助けとして付記しております。正式な解釈は英文に基づき行われます。

Note: The above Japanese text is for the purpose of helping the understanding of the reader. The interpretation of the Assignment should be based on the English text.

譲渡証(続き)  
ASSIGNMENT (Cont.)

署名: Yohsei Oda  
Signature: \_\_\_\_\_  
第 1 発明者: **Youhei Oda**  
First Inventor: \_\_\_\_\_

署名日: September 19, 2014  
Date: \_\_\_\_\_

署名: Yoshitaka Noda  
Signature: \_\_\_\_\_  
第 2 発明者: **Yoshitaka Noda**  
Second Inventor: \_\_\_\_\_

署名日: September 24, 2014  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 3 発明者: \_\_\_\_\_  
Third Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 4 発明者: \_\_\_\_\_  
Fourth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 5 発明者: \_\_\_\_\_  
Fifth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 6 発明者: \_\_\_\_\_  
Sixth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 7 発明者: \_\_\_\_\_  
Seventh Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 8 発明者: \_\_\_\_\_  
Eighth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 9 発明者: \_\_\_\_\_  
Ninth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_

署名: \_\_\_\_\_  
Signature: \_\_\_\_\_  
第 10 発明者: \_\_\_\_\_  
Tenth Inventor: \_\_\_\_\_

署名日: \_\_\_\_\_  
Date: \_\_\_\_\_